


SOP-8
Pin Definition:

- | | |
|-------------|------------|
| 1. Source 1 | 8. Drain 1 |
| 2. Gate 1 | 7. Drain 1 |
| 3. Source 2 | 6. Drain 2 |
| 4. Gate 2 | 5. Drain 2 |

MOSFET PRODUCT SUMMARY

	V_{DS} (V)	R_{DS(on)}(mΩ)	I_D (A)
N-Channel	30	28 @ V _{GS} = 10V	6.5
		42 @ V _{GS} = 4.5V	5.0
P-Channel	-30	65 @ V _{GS} = -10V	-4.2
		90 @ V _{GS} = -4.5V	-3.5

Features

- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

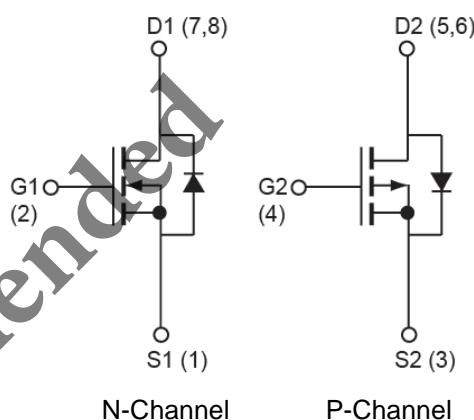
Application

- Load Switch
- PA Switch

Ordering Information

Part No.	Package	Packing
TSM4539DCS RLG	SOP-8	2.5Kpcs / 13" Reel

Note: "G" denote for Halogen Free Product

Block Diagram

N-Channel
P-Channel
MOSFET Absolute Maximum Rating (T_A=25°C unless otherwise noted)

Parameter	Symbol	N-CH Limit	P-CH Limit	Unit
Drain-Source Voltage	V _{DS}	30	-30	V
Gate-Source Voltage	V _{GS}	±20	±20	V
Continuous Drain Current, V _{GS}	I _D	6.5	-4.2	A
Pulsed Drain Current,	I _{DM}	28	-20	A
Drain-Source Diode Forward Current	I _S	2.5	-1.9	A
Power Dissipation @ Ta = 25°C	P _D	2.1	2.1	W
Operating Junction Temperature	T _J	150		°C
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 ~ +150		°C

Thermal Performance

Parameter	Symbol	N-CH Limit	P-CH Limit	Unit
Junction to Ambient Thermal Resistance	R _{θ_{JA}}	62.5	62.5	°C/W
Junction to Lead Thermal Resistance	R _{θ_{JL}}	40	40	°C/W

Notes:

- a. Pulse width limited by the Maximum junction temperature
- b. Surface Mounted on FR4 Board using 1 inch sq pad size, t ≤ 5sec.
- c. Surge Applied at Rated Load Conditions, Half-Wave, Single Phase, 60Hz.

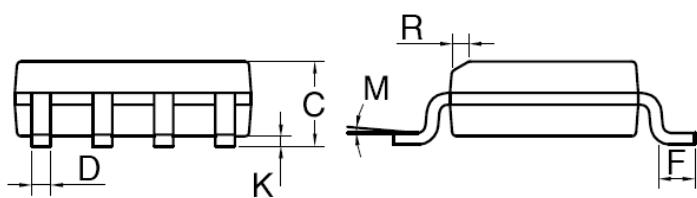
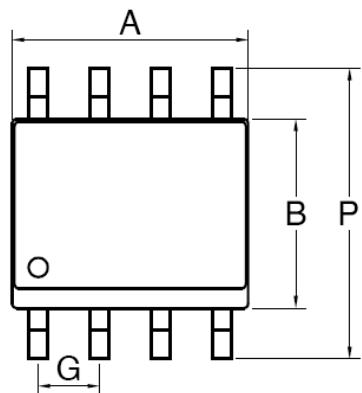
Electrical Specifications ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D = 250\mu\text{A}$	BV_{DSS}	N-CH	30	--	--
	$V_{GS}=0\text{V}, I_D = -250\mu\text{A}$		P-CH	-30	--	--
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(\text{TH})}$	N-CH	1.0	1.4	3.0
	$V_{DS}=V_{GS}, I_D = -250\mu\text{A}$		P-CH	-1.0	-1.5	-3.0
Gate Body Leakage	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	I_{GSS}	N-CH	--	--	± 100
	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$		P-CH	--	--	± 10
Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS} = 0\text{V}$	I_{DSS}	N-CH	--	--	1
	$V_{DS}=-24\text{V}, V_{GS} = 0\text{V}$		P-CH	--	--	-1
Drain-Source On-State Resistance ^a	$V_{GS}=10\text{V}, I_D = 6.5\text{A}$	$R_{DS(\text{ON})}$	N-CH	--	23	28
	$V_{GS}=-10\text{V}, I_D = -4.2\text{A}$		P-CH	--	50	65
	$V_{GS}=4.5\text{V}, I_D = 5\text{A}$		N-CH	--	35	42
	$V_{GS}=-4.5\text{V}, I_D = -3.5\text{A}$		P-CH	--	82	90
Dynamic^b						
Total Gate Charge	N-Channel $V_{DS}=10\text{V}, I_D = 1\text{A}, V_{GS}=10\text{V}$	Q_g	N-CH	--	7	--
			P-CH	--	9.7	--
Gate-Source Charge	P-Channel $V_{DS}=-15\text{V}, I_D = -5.2\text{A}, V_{GS}=-10\text{V}$	Q_{gs}	N-CH	--	1.6	--
			P-CH	--	1.6	--
Gate-Drain Charge	N-Channel $V_{DS}=15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	Q_{gd}	N-CH	--	1.0	--
			P-CH	--	1.3	--
Input Capacitance	P-Channel $V_{DS}=-15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	C_{iss}	N-CH	--	610	--
			P-CH	--	100	--
Output Capacitance	N-Channel $V_{DS}=-15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	C_{oss}	N-CH	--	77	--
			P-CH	--	551	--
Reverse Transfer Capacitance	N-Channel $V_{DS}=15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	C_{rss}	N-CH	--	90	--
			P-CH	--	60	--
Switching^b						
Turn-On Delay Time	N-Channel $V_{DD}=15\text{V}, I_D = 1\text{A}, V_{GEN}=10\text{V}, R_G = 6\Omega$	$t_{d(on)}$	N-CH	--	7	--
			P-CH	--	6.2	--
Turn-On Rise Time		t_r	N-CH	--	10	--
			P-CH	--	6.2	--
Turn-Off Delay Time	P-Channel $V_{DD}=-15\text{V}, I_D = -1\text{A}, V_{GEN}=-10\text{V}, R_G = 6\Omega$	$t_{d(off)}$	N-CH	--	16	--
			P-CH	--	26	--
Turn-Off Fall Time		t_f	N-CH	--	7	--
			P-CH	--	5.5	--
Diode Forward Voltage	$I_S = 1\text{ A}, V_{GS} = 0\text{V}$	V_{SD}	N-CH	--	--	1.0
	$I_S = -1.9\text{A}, V_{GS} = 0\text{V}$		P-CH	--	--	-1.3

Notes:

- a. Pulse test: PW $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
b. For DESIGN AID ONLY, not subject to production testing.

SOP-8 Mechanical Drawing



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX.
A	4.80	5.00	0.189	0.196
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27BSC		0.05BSC	
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

Not Recommended

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